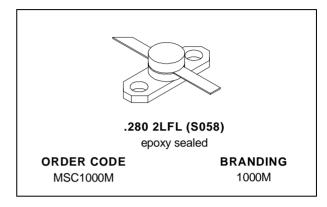


MSC1000M

RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- RUGGEDIZED VSWR ∞:1
- INPUT MATCHING
- LOW THERMAL RESISTANCE
- CLASS A OPERATION
- P_{OUT} = 0.6 W MIN. WITH 10.8 dB GAIN

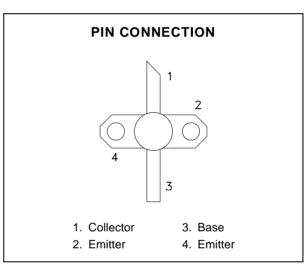


DESCRIPTION

The MSC1000M is a Class A, common emitter transistor with an emitter ballasted Matrix geometry specifically designed for DME/IFF driver applications.

This device is capable of withstanding a ∞:1 load VSWR at any phase angle under full rated conditions. Low RF thermal resistance and semi-automatic wire bonding techniques ensure high reliability and product consistency.

The MSC1000M is housed in the IMPAC $^{\text{TM}}$ package with internal input matching.



ABSOLUTE MAXIMUM RATINGS (T_{case} = 25°C)

Symbol	Parameter	Value	Unit
P _{DISS}	Power Dissipation* (See Safe Area)	_	W
Ic	Device Current*	300	mA
V _{CE}	Collector-Emitter Bias Voltage*	20	V
TJ	Junction Temperature (Pulsed RF Operation)	200	°C
T _{STG}	Storage Temperature	- 65 to +150	°C

THERMAL DATA

IN H(I-C) JUHCHOH-CASE THEITHAI INESISTANCE JJ JJ C/W	R _{TH(i-c)}	Junction-Case Thermal Resistance*	35	°C/W
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^{*}Applies only to rated RF amplifier operation

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ELECTRICAL SPECIFICATIONS (T_{case} = 25°C)

STATIC

Symbol	Test Conditions	Value			1114		
		Min.	Тур.	Max.	Unit		
BV _{CBO}	I _C = 1mA	$I_E = 0mA$		50	_	_	V
BV _{EBO}	I _E = 1mA	$I_C = 0mA$		3.5	_		V
BVCEO	IC = 5mA	$I_B = 0mA$		20	_	_	V
ICES	V _{CE} = 28V			_	_	1.0	mA
hfE	V _{CE} = 5V	I _C = 100mA		15	_	120	_

DYNAMIC

Symbol	I Test Conditions		Value			IIn:4
Symbol			Min.	Тур.	Max.	Unit
Pout	f = 1025 — 1150 MHz P _{IN} = 50 mW	V _{CE} = 18 V	0.6	0.85	_	W
G _P	f = 1025 — 1150 MHz P _{IN} = 50 mW	V _{CE} = 18 V	10.8	12.3	_	dB

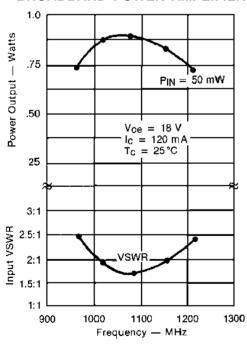
Note: Pulse Width = $10\mu Sec$

 $I_C = 120 \text{mA}$

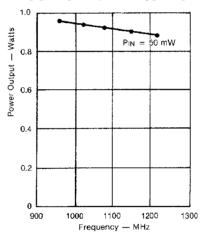
Duty Cycle = 1%

TYPICAL PERFORMANCE

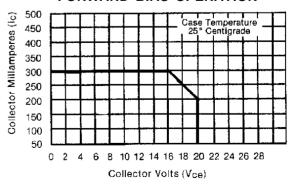
BROADBAND POWER AMPLIFIER



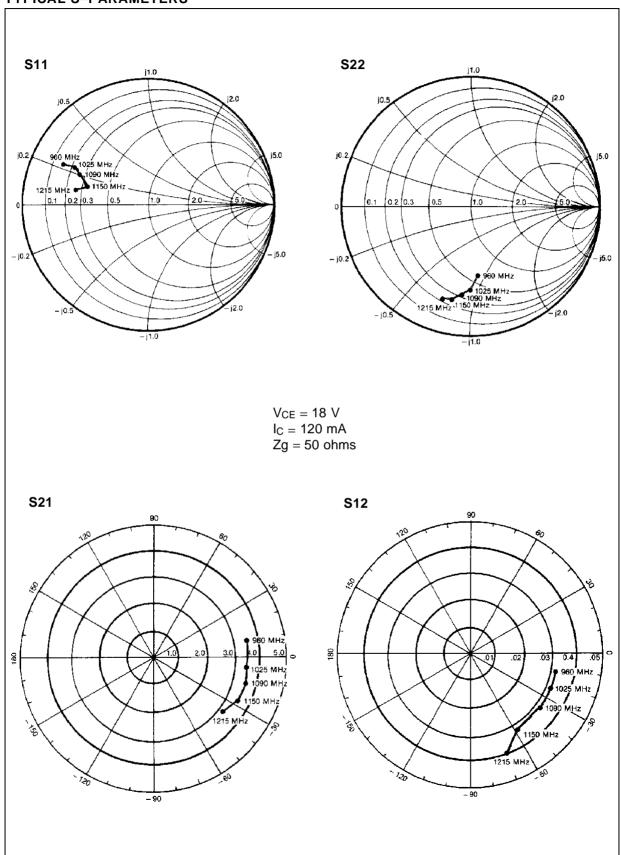
NARROWBAND POWER OUTPUT vs FREQUENCY



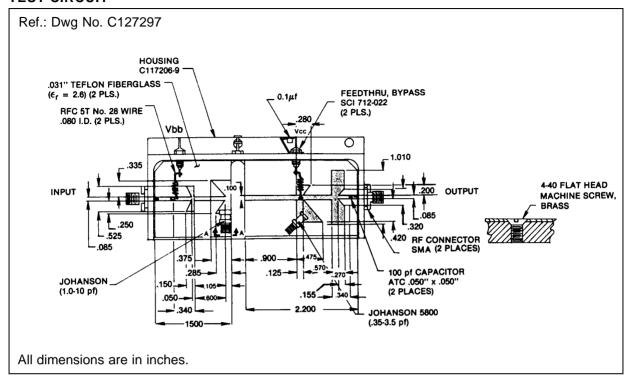
MAXIMUM OPERATING AREA for FORWARD BIAS OPERATION



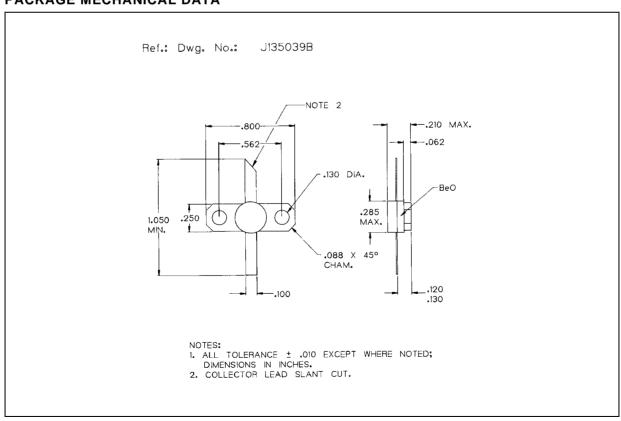
TYPICAL S-PARAMETERS



TEST CIRCUIT



PACKAGE MECHANICAL DATA



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